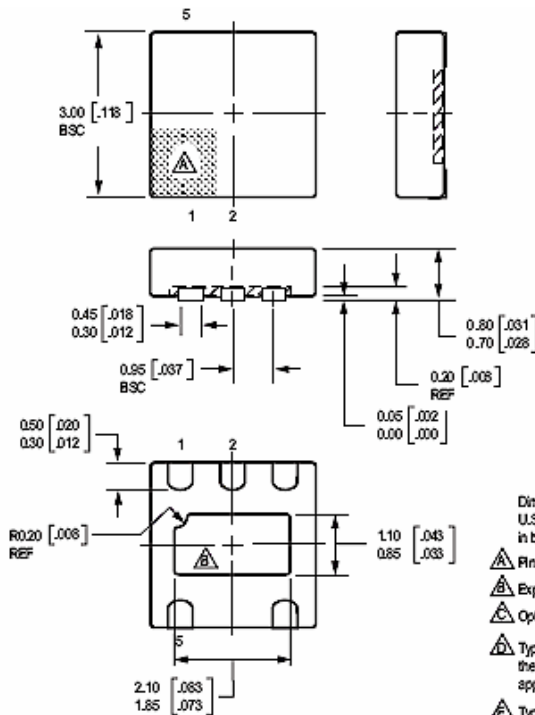**MLP/DFN -5 Package:**

Dimensions in millimeters
U.S. Customary dimensions (in.)
in brackets, for reference only

⚠ Pin index area

⚠ Exposed thermal pad

⚠ Optional thermal vias, ⌀0.30 [.012], pitch 1.2 [.047]

⚠ Typical pad layout including solder pad for exposed thermal pad; adjust as necessary to meet application process requirements

⚠ Typical pad layout with contact pads only; adjust as necessary to meet application process requirements

3.00 [.118] BSC

0.45 [.018] / 0.30 [.012]

0.95 [.037] BSC

0.80 [.031] / 0.70 [.028]

0.20 [.008] REF

0.05 [.002] / 0.00 [.000]

0.50 [.020] / 0.30 [.012]

R0.20 [.008] REF

1.10 [.043] / 0.85 [.033]

2.10 [.083] / 1.85 [.073]

0.75 [.030] NOM

0.50 [.020] MIN

3.40 [.134] REF

0.95 [.037] BSC

0.75 [.030] NOM

0.15 [.006] MIN

0.50 [.020] MIN

1.10 [.043] MAX

3.40 [.134] REF

0.20 [.008] REF

0.95 [.037] BSC

2.10 [.083] MAX